Amendments to the Specification:

Please replace the paragraph beginning on page 12, line 18, with the following amended paragraph:

As more specific examples of the high molecular weight surfactant, a fatty acid salt, rosin acid salt, alkyl polyoxyethylene sulfate, α-olefin sulfonate, alkyl naphthalene sulfonate, lignin sulfonate, alkyl phosphate, primary amine salt, alkyl trimethyl ammonium salt, alkyl polyoxyethylene amine, N-alkyl β-aminopropionic acid, N-alkyl sulfobetaine, N-alkylhydroxyl sulfobetaine, lecithin, ~~silkyl~~ alkyl polyoxyethylene ether, fatty acid polyoxyethylene ester, fatty acid sorbitan ester, fatty acid sucrose ester, 1,3-dioxalane polymer, polypropylene glycol, polypropylene propanol, polyethylene glycol, polyethylene glycol derivative, oxylalkylene polymer, copolymer of ethylene oxide and propylene oxide, and fatty acid polyglycerol ester can be given.

Please replace the paragraph beginning on page 32, line 18, with the following amended paragraph:

An amphoteric surfactant such as lauryl amide ~~propyl~~ propionic acid betaine, lauryl aminoacetic acid betaine, or the like may be used instead of the nonionic surfactant exhibiting cationic properties under strongly acidic conditions.

Please replace the paragraph beginning on page 37, line 13, with the following amended paragraph:

The relation between the sulfuric acid concentration and electric conductivity of the copper sulfate plating solution is shown in Figure 7, which shows that conventional plating without using an electric resistor was effected at the sulfuric acid concentration in the range of 10-60 g/l and the electric conductivity in the range of 6-20 S/m. In contrast, based on the fact that plating was possible at the electric conductivity of 3 S/m or less as shown in Figures ~~2 and 3~~ 1 and 2, it can be judged that excellent in-plane uniformity was achieved when an electric resistor was used.